



南京时恒电子科技有限公司

规格承认书

APPROVAL SHEET

客户名称:

CUSTOMER _____

产品名称:

PART NAME _____

片式 NTC 热敏电阻规格书

产品规格:

PART NUMBER _____

CMFB 103F3435

日期:

DATE _____

2020 年 08 月 21 日

确 认

CONFIRM

客户	供货商/制造商
品保部: _____	规格书制作: <u>鞠晓丽</u>
制造部: _____	业务员审核: _____
工程部: _____	技术部审核: <u>程鹏</u>
	品质部审核: <u>李昕媛</u>

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1. 外形尺寸 Shape and Dimensions

- 尺寸：见图 1 和表 1
- PCB 焊盘：见图 2 和表 1

Dimensions: See Fig.1 and Table 1.

Recommended PCB pattern for reflow soldering: See Fig.2 and Table 1.

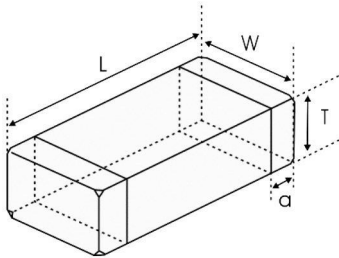


图 1 Fig.1

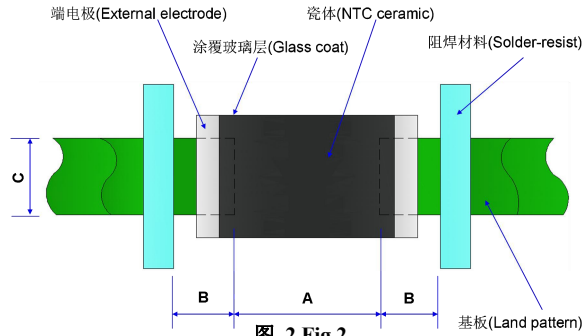


图 2 Fig.2

表 1 (Table 1)

单位 unit: inch[mm]

类别 Type	L	W	T	a	A	B	C
0805 [2012]	0.079±0.008 [2.0±0.2]	0.049±0.008 [1.25±0.2]	0.033±0.008 [0.85±0.2]	0.020±0.012 [0.5±0.3]	[1.0-1.1]	[0.6-0.7]	[10.-1.2]

2. 产品标识 (料号) Product Identification(Part Number)

CMF B 103 F 3435
① ② ③ ④ ⑤

①类别 Type		③25°C的零功率电阻 Nominal Zero-Power Resistance		⑤B 值常数 B Constant			
CMF	片式NTC 热敏电阻器 Chip NTC Thermistor	222	2.2kΩ	3435	3435K		
② 外形尺寸(mm) External Dimensions (L×W)		103	10kΩ	3950	3950K		
		104	100kΩ	4250	4250K		
A	1.6×0.8	④电阻值公差 Tolerance of Resistance					
B	2.0×1.2						
						F	±1%
						G	±2%
						H	±3%
		J	±5%				

3. 电气特性 Electrical Characteristics

型号 Part No	电阻值 Resistance (25°C) (kΩ)	B 常数B Constant (25/50°C) (K)	B 常数B Constant (25/85°C) (K)	允许工作电流 Permissible Operating Current (25°C) (mA)	耗散系数 Dissipation Factor (mW/°C)	热时间常数 Thermal Time Constant (s)	额定功率 Rated Electric Power (25°C) (mW)	工作温度 Operating ambient temperature (°C)
CMFB 103F3435	10	3380	3435	0.44	1.0	<5	100	-40~+125

检验和测试程序

测试条件

如无特别规定，检验和测试的标准大气环境条件如下：

- a. 环境温度：20±15℃；
- b. 相对湿度：65±20%；
- c. 气压：86 kPa~106 kPa

如果对测试结果有异议，则在下述条件下测试：

- a. 环境温度：20±2℃；
- b. 相对湿度：65±5%RH；
- c. 气压：86kPa ~ 106kPa

检查设备

外观检查：20 倍放大镜；
阻值检查：热敏电阻测试仪

4 Test and Measurement Procedures

Test Conditions

Unless otherwise specified, the standard atmospheric conditions for measurement/test as:

- a. Ambient Temperature: 20±15℃
- b. Relative Humidity: 65±20%
- c. Air Pressure: 86kPa to 106kPa

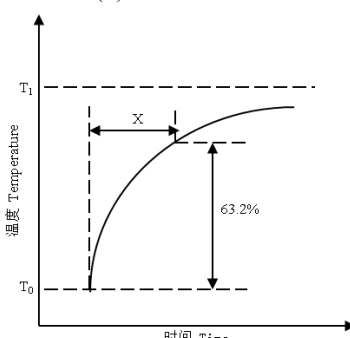
If any doubt on the results, measurements/tests should be made within the following limits:

- a. Ambient Temperature: 20±2℃
- b. Relative Humidity: 65±5%
- c. Air Pressure: 86kPa to 106kPa

Inspection Equipment

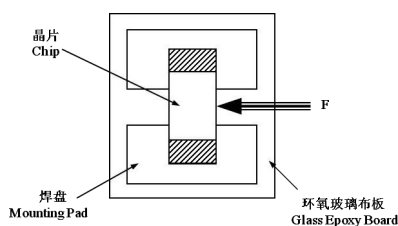
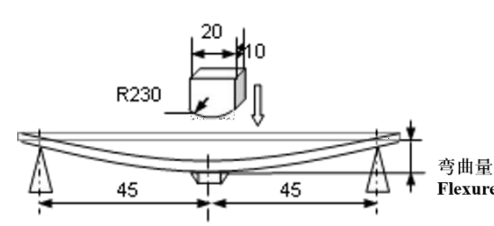
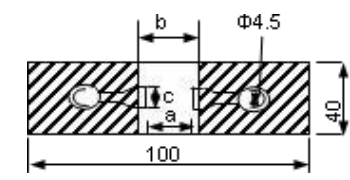
Visual Examination: 20×magnifier
Resistance value test: Thermistor resistance tester

1 电性测试 Electrical Test

序号 No.	项目 Items	测试方法及备注 Test Methods and Remarks
1	25℃零功率电阻值 Nominal Zero-Power Resistance at 25℃ (R25)	环境温度 Ambient temperature: 25±0.2℃ 测试功率 Measuring electric power: ≤0.1mW
2	B 值常数 Nominal B Constant	分别在环境温度 25±0.2℃, 50±0.2℃或 85±0.2℃下测量电阻值。 Measure the resistance at the ambient temperature of 25±0.2℃, 50±0.2℃ or 85±0.2℃. $B(25-50^{\circ}\text{C}) = \frac{\ln R_{25} - \ln R_{50}}{\frac{1}{T_{25}} - \frac{1}{T_{50}}}$ $B(25-85^{\circ}\text{C}) = \frac{\ln R_{25} - \ln R_{85}}{\frac{1}{T_{25}} - \frac{1}{T_{85}}}$ T: 绝对温度 (K) Absolute temperature (K)
3	热时间常数 Thermal Time Constant	在零功率条件下，当热敏电阻的环境温度发生急剧变化时，热敏电阻元件产生最初温度 T ₀ 与最终温度 T ₁ 两者温度差的 63.2% 的温度变化所需要的时间，通常以秒(S)表示。 The total time for the temperature of the thermistor to change by 63.2% of the difference from ambient temperature T ₀ (°C) to T ₁ (°C) by the drastic change of the power applied to thermistor from Non-zero Power to Zero-Power state, normally expressed in second(S). 

4	耗散系数 Dissipation Factor	在一定环境温度下，NTC 热敏电阻通过自身发热使其温度升高 1℃时所需要的功率，通常以 mW/℃表示。可由下面公式计算： The required power which makes the NTC thermistor body temperature raise 1 °C through self-heated, normally expressed in milliwatts per degree Celsius (mW/ °C). It can be calculated by the following formula: $\delta = \frac{W}{T-T_0}$
5	额定功率 Rated Power	在环境温度 25℃下因自身发热使表面温度升高 100℃所需要的功率。 The necessary electric power makes thermistor's temperature rise 100°C by self-heating at ambient temperature 25°C.
6	允许工作电流 Permissible operating current	在静止空气中通过自身发热使其升温为 1℃的电流。 The current that keep body temperature of chip NTC on the PC board in still air rising 1°C by self-heating.

5 信赖性试验 Reliability Test

项目 Items	测试标准 Standard	测试方法及备注 Test Methods and Remarks	要求 Requirements																				
端头附着力 Terminal Strength	IEC 60068-2-21	① 将晶片焊接在测试基板上（如右图所示的环氧玻璃布板），按箭头所示方向施加作用力； Solder the chip to the testing jig (glass epoxy board shown in the right) using eutectic solder. Then apply a force in the direction of the arrow. ② 0201、0402 和 0603 系列施加 5N 的作用力，0805 系列产品施加 10N 的作用力； 5N force for 0201, 0402 and 0603 series, 10N force for 0805 series. ③ 保持时间 Duration: 10±1s	端电极无脱落且瓷体无损伤。 No removal or split of the termination or other defects shall occur. 																				
抗弯强度 Resistance to Flexure	IEC 60068-2-21	① 将晶片焊接在测试基板上（如右图所示的环氧玻璃布板），按下图箭头所示方向施加作用力； Solder the chip to the test jig (glass epoxy board shown in the right) using a eutectic solder. Then apply a force in the direction shown as follow; ② 弯曲变形量 Flexure 0201: 1mm 0402, 0603, 0805: 2mm ③ 施压速度 Pressurizing Speed: <0.5mm/s; ④ 保持时间 Duration: 10s 	① 无外观损伤。 No visible damage. ② 试验前后 R25 的变化率：±5%以内； R25 variation: within ±5% 单位 unit: mm <table border="1" data-bbox="1101 1344 1468 1568"> <thead> <tr> <th>类型 Type</th> <th>a</th> <th>b</th> <th>c</th> </tr> </thead> <tbody> <tr> <td>0201</td> <td>0.25</td> <td>0.3</td> <td>0.3</td> </tr> <tr> <td>0402</td> <td>0.4</td> <td>1.5</td> <td>0.5</td> </tr> <tr> <td>0603</td> <td>1.0</td> <td>3.0</td> <td>1.2</td> </tr> <tr> <td>0805</td> <td>1.2</td> <td>4.0</td> <td>1.65</td> </tr> </tbody> </table> 	类型 Type	a	b	c	0201	0.25	0.3	0.3	0402	0.4	1.5	0.5	0603	1.0	3.0	1.2	0805	1.2	4.0	1.65
类型 Type	a	b	c																				
0201	0.25	0.3	0.3																				
0402	0.4	1.5	0.5																				
0603	1.0	3.0	1.2																				
0805	1.2	4.0	1.65																				

振动 Vibration	IEC 60068-2-80	<p>① 将晶片焊接在测试基板上（如右图所示的环氧玻璃布板）； Solder the chip to the testing jig (glass epoxy board shown in the left) using eutectic solder.</p> <p>② 晶片以全振幅为 1.5mm 进行振动，频率范围为 10Hz ~ 55 Hz； The chip shall be subjected to a simple harmonic motion having total amplitude of 1.5mm, the frequency being varied uniformly between the approximate limits of 10 and 55 Hz.</p> <p>③ 振动频率按 10Hz→55Hz→10Hz 循环，周期为 1 分钟，在空间三个互相垂直的方向上各振动 2 小时（共 6 小时）。 The frequency ranges from 10 to 55 Hz and return to 10 Hz shall be traversed in approximately 1 minute. This motion shall be applied for a period of 2 hours in each 3 mutually perpendicular directions (total of 6 hours).</p>	无外观损伤。 No visible damage. <div style="text-align: center;">  </div>															
坠落 Dropping	IEC 60068-2-32	从 1m 的高度让晶片自由坠落至水泥地面 10 次。 Drop a chip 10 times on a concrete floor from a height of 1 meter.	无外观损伤。 No visible damage.															
可焊性 Solderability	IEC 60068-2-58	<p>① 焊接温度 Solder temperature: 245±5℃.</p> <p>② 浸渍时间 Duration: 3±0.3s.</p> <p>③ 焊锡成分 Solder: Sn/3.0Ag/0.5Cu.</p> <p>④ 助焊剂 Flux: (重量比) 25%松香和 75%酒精 25% Resin and 75% ethanol in weight.</p>	<p>① 无外观损伤； No visible damage.</p> <p>② 元件端电极的焊锡覆盖率不小于 95%。 Wetting shall exceed 95% coverage.</p>															
耐焊性 Resistance to Soldering Heat	IEC 60068-2-58	<p>① 焊接温度 Solder temperature: 260±5℃.</p> <p>② 浸渍时间 Duration: 10±1s.</p> <p>③ 焊锡成分 Solder: Sn/3.0Ag/0.5Cu.</p> <p>④ 助焊剂 Flux: (重量比) 25%松香和 75%酒精 25% Resin and 75% ethanol in weight.</p> <p>⑤ 试验后标准条件下放置 1~2 小时后测量。 The chip shall be stabilized at normal condition for 1~2 hours before measuring.</p>	<p>① 无外观损伤； No visible damage.</p> <p>② 试验前后 R25 的变化率：±3%以内； R25 variation: within ±3%</p> <p>③ 试验前后 B 值的变化率：±2%以内。 B constant variation: within ±2%</p>															
温度周期 Temperature cycling	IEC 60068-2-14	<p>① 无负载于下表所示的环境条件下重复 5 次。 5 cycles of following sequence without loading.</p> <table border="1" data-bbox="475 1370 1024 1563"> <thead> <tr> <th>步骤 Step</th> <th>温度 Temperature</th> <th>时间 Time</th> </tr> </thead> <tbody> <tr> <td>1</td> <td>-40±5℃</td> <td>30±3min</td> </tr> <tr> <td>2</td> <td>25±2℃</td> <td>5±3min</td> </tr> <tr> <td>3</td> <td>125±2℃</td> <td>30±3min</td> </tr> <tr> <td>4</td> <td>25±2℃</td> <td>5±3min</td> </tr> </tbody> </table> <p>② 试验后标准条件下放置 1~2 小时后测量。 The chip shall be stabilized at normal condition for 1~2 hours before measuring.</p>	步骤 Step	温度 Temperature	时间 Time	1	-40±5℃	30±3min	2	25±2℃	5±3min	3	125±2℃	30±3min	4	25±2℃	5±3min	<p>① 无外观损伤； No visible damage.</p> <p>② 试验前后 R25 的变化率：±3%以内； R25 variation: within ±3%</p> <p>③ 试验前后 B 值的变化率：±2%以内。 B constant variation: within ±2%</p>
步骤 Step	温度 Temperature	时间 Time																
1	-40±5℃	30±3min																
2	25±2℃	5±3min																
3	125±2℃	30±3min																
4	25±2℃	5±3min																
高温存放 Resistance to dry heat	IEC 60068-2-2	<p>① 在 125±5℃ 空气中，无负载放置 1000±24 小时。 125±5℃ in air, for 1000±24 hours without loading.</p> <p>② 试验后标准条件下放置 1~2 小时后测量。 The chip shall be stabilized at normal condition for 1~2 hours before measuring.</p>	<p>① 无外观损伤； No visible damage.</p> <p>② 试验前后 R25 的变化率：±5%以内； R25 variation: within ±5%</p> <p>③ 试验前后 B 值的变化率：±2%以内。 B constant variation: within ±2%</p>															

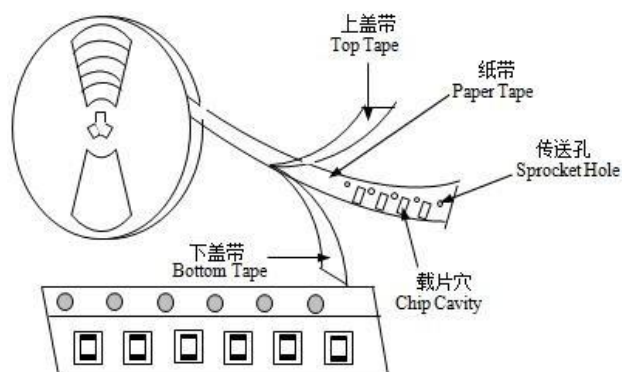
低温存放 Resistance to cold	IEC 60068-2-1	① 在-40±3℃空气中，无负载放置 1000±24 小时。 -40±3℃ in air, for 1000±24 hours without loading. ② 试验后标准条件下放置 1~2 小时后测量。 The chip shall be stabilized at normal condition for 1~2 hours before measuring.	① 无外观损伤； No visible damage. ② 试验前后 R25 的变化率：±5%以内； R25 variation: within ±5% ③ 试验前后 B 值的变化率：±2%以内。 B constant variation: within ±2%
湿热存放 Resistance to damp heat	IEC 60068-2-78	① 在 40±2℃，相对湿度 90~95%空气中，无负载放置 1000±24 小时。 40±2℃, 90~95%RH in air, for 1000±24 hours without loading. ② 试验后标准条件下放置 1~2 小时后测量。 The chip shall be stabilized at normal condition for 1~2 hours before measuring.	① 无外观损伤； No visible damage. ② 试验前后 R25 的变化率：±3%以内； R25 variation: within ±3% ③ 试验前后 B 值的变化率：±2%以内。 B constant variation: within ±2%
高温负荷 Resistance to high temperature load	IEC 60539-1 5.25.4	① 在 85±2℃空气中，施加允许工作电流1000±48 小时。 85±2℃ in air with permissive operating current for 1000±48 hours ② 试验后标准条件下放置 1~2 小时后测量。 The chip shall be stabilized at normal condition for 1~2 hours before measuring.	① 无外观损伤； No visible damage. ② 试验前后 R25 的变化率：±5%以内； R25 variation: within ±5% ③ 试验前后 B 值的变化率：±2%以内。 B constant variation: within ±2%

6 编带和储存 Taping & Storage

编带 Taping

类型 Type	0201	0402	0603	0805
编带厚度 Tape thickness(mm)	0.5±0.15	0.5±0.15	0.8±0.15	0.85±0.2
编带材质 Tape material	纸带 Paper Tape			
每盘数量 Quantity per Reel	15K	10K	4K	4K

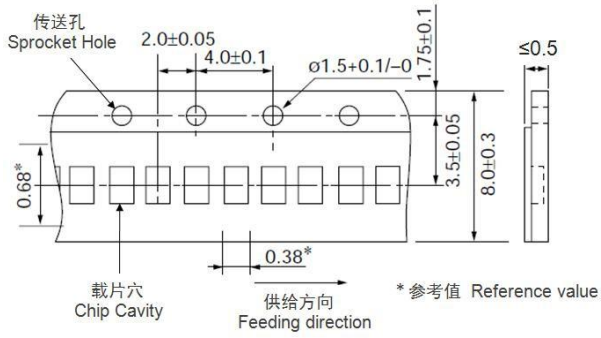
(1) 编带图 Taping Drawings



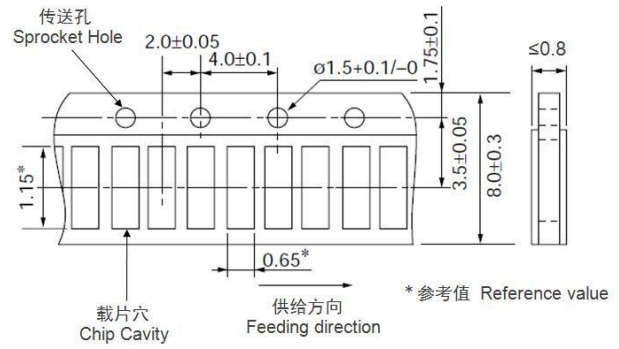
(2) 纸带尺寸 Paper Tape Dimensions

(单位 Unit: mm)

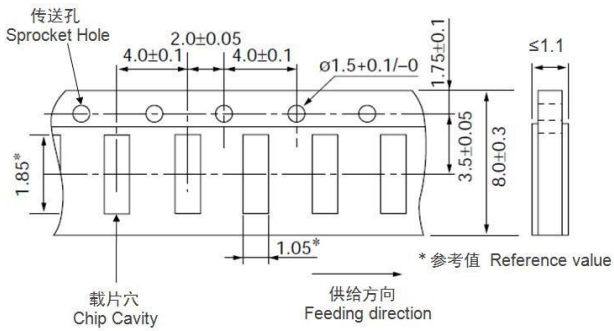
0201 系列 0201 series



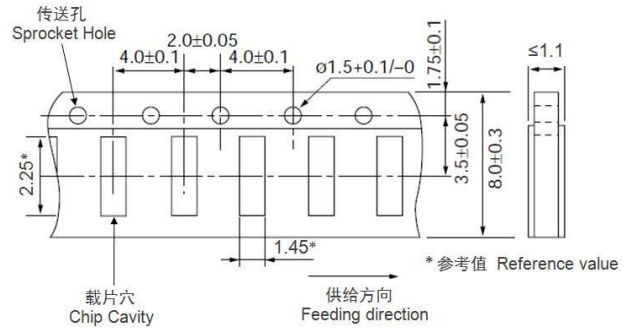
0402 系列 0402 series



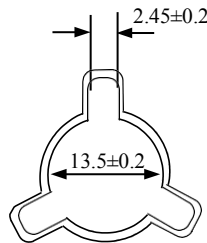
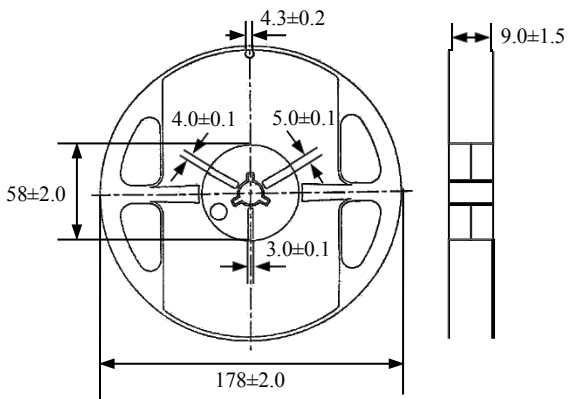
0603 系列 0603 series



0805 系列 0805 series



(3) 卷盘尺寸 Reel Dimensions(单位 Unit: mm)



7 储存

• 储存条件

a. 储存温度: $-10^{\circ}\text{C} \sim 40^{\circ}\text{C}$

b. 相对湿度: $\leq 75\% \text{RH}$

c. 避免接触粉尘、腐蚀性气氛和阳光

• 储存期限: 6个月

8 注意事项

- 系列热敏电阻不可在以下条件下工作或储存：
 - (1) 腐蚀性气体或还原性气体
(氯气、硫化氢气体、氨气、硫酸气体、一氧化氮等)。
 - (2) 挥发性或易燃性气体
 - (3) 多尘条件
 - (4) 高压或低压条件
 - (5) 潮湿场所
 - (6) 存在盐水、油、化学液体或有机溶剂的场所
 - (7) 强烈振动
 - (8) 存在类似有害条件的其他场所
- 系列热敏电阻的陶瓷属于易碎材料，使用时不可施加过大压力或冲击。
- 系列热敏电阻不可在超过目录规定的温度范围情况下工作。

7 Storage

- **Storage Conditions**
 - a. Storage Temperature: $-10^{\circ}\text{C} \sim 40^{\circ}\text{C}$

b. Relative Humidity: $\leq 75\%RH$

c. Keep away from corrosive atmosphere and sunlight.

- **Period of Storage: 6 Months**

8 Notes & Warnings

- The series thermistors shall not be operated and stored under the following environmental condition:
 - (1) Corrosive or deoxidized atmospheres
(such as chlorine, sulfurated hydrogen, ammonia, sulfuric acid, nitric oxide and so on)
 - (2) Volatile or inflammable atmospheres
 - (3) Dusty condition
 - (4) Excessive high or low pressure condition
 - (5) Humid site
 - (6) Places with brine, oil, chemical liquid or organic solvent
 - (7) Intense vibration
 - (8) Places with analogously deleterious conditions
- The ceramic body of the series thermistors is fragile, no excessive pressure or impact shall be exerted on it.
- The series thermistors shall not be operated beyond the specified "Operating Temperature Range" in the catalog.

9 建议焊接条件

• 回流焊

温升 1~2°C/sec.

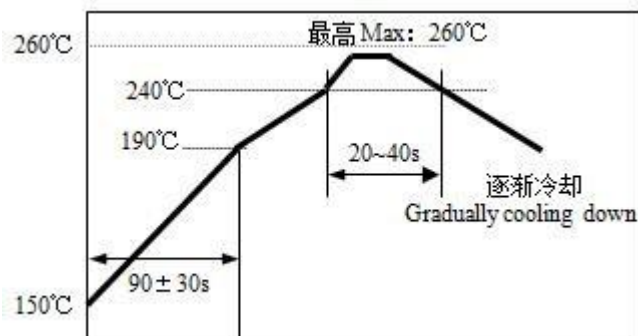
预热: 150~190°C/90±30 sec.

大于 240°C时间: 20~40sec

峰值温度: 最高 260°C/10 sec.

焊锡: Sn/3.0Ag/0.5Cu

回流焊: 最多 2 次



9 Recommended Soldering Technologies

• Re-flowing Profile

1~2°C/sec. Ramp

Pre-heating: 150~190°C/90±30 sec.

Time above 240°C: 20~40 sec.

Peak temperature: 260°C Max./10 sec.

Solder paste: Sn/3.0Ag/0.5Cu

Max.2 times for re-flowing.

• 手工焊

烙铁功率: 最大 30W

预热: 150°C/60 sec.

烙铁头温度: 最高 350°C

焊接时间: 最多 3sec.

焊锡: Sn/3.0Ag/0.5Cu

手工焊: 最多 1 次

• Iron Soldering Profile

Iron soldering power: Max.30W

Pre-heating: 150°C/60 sec.

Soldering Tip temperature: 350°C Max.

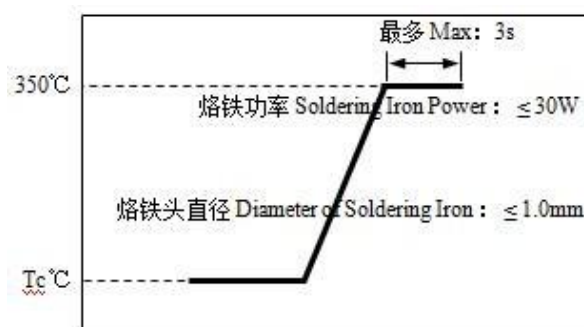
Soldering time: 3 sec Max.

Solder paste: Sn/3.0Ag/0.5Cu

Max.1 times for iron soldering

[注: 不要使烙铁头接触到端头]

[Note: Take care not to apply the tip of the soldering iron to the terminal electrodes.]



10 R-T 表 R-T table

温度 Temp. (°C)	R 最小值 R_Min (Kohm)	R 中心值 R_Cent (Kohm)	R 最大值 R_Max (Kohm)	阻值公差 Res TOL.	温度公差 Temp. TOL.(°C)
-40	189.674	197.390	205.400	4.06%	0.69
-39	179.349	186.540	194.000	4.00%	0.69
-38	169.647	176.350	183.299	3.94%	0.68
-37	160.550	166.800	173.276	3.88%	0.68
-36	151.990	157.820	163.857	3.83%	0.67
-35	143.951	149.390	155.019	3.77%	0.67
-34	136.431	141.510	146.763	3.71%	0.66
-33	129.347	134.090	138.993	3.66%	0.66
-32	122.680	127.110	131.687	3.60%	0.65
-31	116.391	120.530	124.804	3.55%	0.65
-30	110.472	114.340	118.332	3.49%	0.64
-29	104.913	108.530	112.260	3.44%	0.64
-28	99.658	103.040	106.526	3.38%	0.63
-27	94.706	97.870	101.129	3.33%	0.63
-26	90.029	92.989	96.037	3.28%	0.62
-25	85.611	88.381	91.231	3.23%	0.62
-24	81.443	84.036	86.702	3.17%	0.61
-23	77.504	79.931	82.426	3.12%	0.60
-22	73.779	76.052	78.387	3.07%	0.60
-21	70.256	72.384	74.569	3.02%	0.59
-20	66.922	68.915	70.961	2.97%	0.59
-19	63.767	65.634	67.549	2.92%	0.58
-18	60.779	62.529	64.323	2.87%	0.58
-17	57.949	59.589	61.269	2.82%	0.57
-16	55.268	56.804	58.377	2.77%	0.56
-15	52.726	54.166	55.640	2.72%	0.56
-14	50.315	51.665	53.046	2.67%	0.55
-13	48.029	49.294	50.588	2.62%	0.55
-12	45.860	47.046	48.258	2.58%	0.54
-11	43.801	44.913	46.049	2.53%	0.53
-10	41.846	42.889	43.953	2.48%	0.53
-9	39.989	40.967	41.964	2.43%	0.52
-8	38.225	39.142	40.077	2.39%	0.51
-7	36.549	37.408	38.284	2.34%	0.51
-6	34.955	35.761	36.582	2.30%	0.50
-5	33.440	34.196	34.965	2.25%	0.49
-4	31.998	32.707	33.428	2.20%	0.49
-3	30.627	31.291	31.966	2.16%	0.48
-2	29.322	29.945	30.578	2.11%	0.47
-1	28.080	28.664	29.257	2.07%	0.47

0	26.898	27.445	28.001	2.02%	0.46
1	25.770	26.283	26.804	1.98%	0.45
2	24.696	25.177	25.665	1.94%	0.45
3	23.673	24.124	24.581	1.89%	0.44
4	22.699	23.121	23.549	1.85%	0.43
5	21.769	22.165	22.566	1.81%	0.42
6	20.882	21.253	21.628	1.76%	0.42
7	20.037	20.384	20.735	1.72%	0.41
8	19.230	19.555	19.883	1.68%	0.40
9	18.460	18.764	19.071	1.64%	0.39
10	17.725	18.010	18.297	1.60%	0.39
11	17.024	17.290	17.559	1.55%	0.38
12	16.353	16.602	16.853	1.51%	0.37
13	15.713	15.946	16.181	1.47%	0.36
14	15.101	15.319	15.538	1.43%	0.36
15	14.517	14.720	14.925	1.39%	0.35
16	13.958	14.148	14.339	1.35%	0.34
17	13.424	13.601	13.779	1.31%	0.33
18	12.913	13.078	13.244	1.27%	0.32
19	12.424	12.578	12.733	1.23%	0.32
20	11.955	12.099	12.243	1.19%	0.31
21	11.508	11.642	11.776	1.15%	0.30
22	11.079	11.204	11.329	1.11%	0.29
23	10.669	10.785	10.901	1.08%	0.28
24	10.276	10.384	10.492	1.04%	0.27
25	9.900	10.000	10.100	1.00%	0.27
26	9.532	9.632	9.732	1.04%	0.28
27	9.180	9.280	9.380	1.08%	0.29
28	8.843	8.943	9.042	1.11%	0.30
29	8.520	8.619	8.718	1.15%	0.31
30	8.211	8.309	8.408	1.19%	0.33
31	7.914	8.012	8.110	1.22%	0.34
32	7.630	7.727	7.824	1.26%	0.35
33	7.357	7.453	7.550	1.30%	0.36
34	7.096	7.191	7.287	1.33%	0.37
35	6.845	6.939	7.034	1.37%	0.39
36	6.604	6.698	6.792	1.41%	0.40
37	6.373	6.466	6.559	1.44%	0.41
38	6.152	6.243	6.335	1.48%	0.43
39	5.939	6.029	6.120	1.51%	0.44
40	5.735	5.824	5.914	1.55%	0.45
41	5.538	5.627	5.716	1.58%	0.46
42	5.350	5.437	5.525	1.62%	0.48

43	5.169	5.255	5.342	1.65%	0.49
44	4.995	5.080	5.165	1.69%	0.50
45	4.828	4.911	4.996	1.72%	0.52
46	4.667	4.749	4.832	1.75%	0.53
47	4.512	4.593	4.675	1.79%	0.54
48	4.363	4.443	4.524	1.82%	0.56
49	4.220	4.299	4.379	1.86%	0.57
50	4.083	4.160	4.239	1.89%	0.58
51	3.950	4.027	4.104	1.92%	0.60
52	3.823	3.898	3.974	1.96%	0.61
53	3.700	3.774	3.849	1.99%	0.63
54	3.582	3.654	3.728	2.02%	0.64
55	3.468	3.539	3.612	2.05%	0.65
56	3.358	3.429	3.500	2.09%	0.67
57	3.252	3.322	3.392	2.12%	0.68
58	3.151	3.219	3.288	2.15%	0.70
59	3.052	3.119	3.188	2.18%	0.71
60	2.958	3.024	3.091	2.22%	0.72
61	2.867	2.931	2.997	2.25%	0.74
62	2.779	2.842	2.907	2.28%	0.75
63	2.694	2.756	2.820	2.31%	0.77
64	2.612	2.673	2.736	2.34%	0.78
65	2.533	2.593	2.655	2.37%	0.80
66	2.457	2.516	2.576	2.40%	0.81
67	2.383	2.441	2.501	2.43%	0.83
68	2.312	2.369	2.428	2.46%	0.84
69	2.244	2.300	2.357	2.50%	0.86
70	2.177	2.233	2.289	2.53%	0.87
71	2.113	2.168	2.223	2.56%	0.89
72	2.052	2.105	2.159	2.59%	0.90
73	1.992	2.044	2.098	2.62%	0.92
74	1.934	1.986	2.038	2.65%	0.93
75	1.879	1.929	1.981	2.68%	0.95
76	1.825	1.874	1.925	2.71%	0.96
77	1.773	1.821	1.871	2.73%	0.98
78	1.722	1.770	1.819	2.76%	1.00
79	1.673	1.720	1.768	2.79%	1.01
80	1.626	1.673	1.720	2.82%	1.03
81	1.581	1.626	1.672	2.85%	1.04
82	1.537	1.581	1.627	2.88%	1.06
83	1.494	1.538	1.582	2.91%	1.08
84	1.453	1.496	1.540	2.94%	1.09
85	1.413	1.455	1.498	2.97%	1.11

86	1.374	1.416	1.458	2.99%	1.13
87	1.337	1.377	1.419	3.02%	1.14
88	1.300	1.340	1.381	3.05%	1.16
89	1.265	1.304	1.345	3.08%	1.17
90	1.231	1.270	1.309	3.11%	1.19
91	1.198	1.236	1.275	3.13%	1.21
92	1.167	1.204	1.242	3.16%	1.23
93	1.136	1.172	1.209	3.19%	1.24
94	1.106	1.141	1.178	3.22%	1.26
95	1.076	1.112	1.148	3.24%	1.28
96	1.048	1.083	1.118	3.27%	1.29
97	1.021	1.055	1.090	3.30%	1.31
98	0.995	1.028	1.062	3.32%	1.33
99	0.969	1.002	1.035	3.35%	1.35
100	0.944	0.976	1.009	3.38%	1.36
101	0.920	0.951	0.984	3.40%	1.38
102	0.897	0.927	0.959	3.43%	1.40
103	0.874	0.904	0.935	3.46%	1.42
104	0.852	0.882	0.912	3.48%	1.43
105	0.830	0.860	0.890	3.51%	1.45
106	0.810	0.838	0.868	3.53%	1.47
107	0.790	0.818	0.847	3.56%	1.49
108	0.770	0.798	0.826	3.59%	1.50
109	0.751	0.778	0.806	3.61%	1.52
110	0.733	0.759	0.787	3.64%	1.54
111	0.715	0.741	0.768	3.66%	1.56
112	0.697	0.723	0.750	3.69%	1.58
113	0.680	0.706	0.732	3.71%	1.60
114	0.664	0.689	0.715	3.74%	1.61
115	0.648	0.673	0.698	3.76%	1.63
116	0.633	0.657	0.682	3.79%	1.65
117	0.618	0.641	0.666	3.81%	1.67
118	0.603	0.626	0.650	3.84%	1.69
119	0.589	0.612	0.635	3.86%	1.71
120	0.575	0.598	0.621	3.89%	1.73
121	0.562	0.584	0.607	3.91%	1.75
122	0.549	0.570	0.593	3.93%	1.77
123	0.536	0.557	0.579	3.96%	1.79
124	0.524	0.545	0.566	3.98%	1.80
125	0.512	0.532	0.554	4.01%	1.82

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